### ECTC 2011 Plenary Session

Power Efficiency Challenges and Solutions: From Outer Space to Inside the Human Body

### ECTC 2011 Plenary Session **Power Efficiency Challenges and Solutions**

From Outer Space to Inside the Human Body



- M.S. in EE, Michigan State University, 1995
- M.S. in EE, University of Hanover, Germany, 1996
- Ph.D. in EECS, Massachusetts Institute of Technology, 2001
- At Intel Corporation in Chandler, Arizona, since 2001, working on research in microelectronic packaging
- More than 25 US patents
- Over 70 technical papers
- Senior Member, IEEE
- Past Chair, IEEE Phoenix Section

**Session Chair** 

Henning Braunisch
Principal Engineer, Intel Corporation

#### Introduction

Why is the power efficiency problem important?

- Many microelectronic devices and systems power or energy limited
- At all levels of human activity
- Examples:
  - Communication distance
  - Computing performance
  - Economics of the Internet
  - Environmental impact
  - Thermal issues
  - Battery life
- Let's explore, but first...

### Power Efficiency Challenges and Solutions The Court of C

From Outer Space to Inside the Human Body

#### Introduction (cont'd)

Food for thought!

- From Nicholas Carr's blog Rough Type (2006): Avatars consume as much electricity as Brazilians
- Second World is a popular on-line community where people navigate an "avatar" living in a virtual world
- On average 12,500 avatars are supported by 4,000 servers
- Including the individual personal computers controlling the avatars and datacenter air conditioning, assuming "always on" leads to an annual energy consumption per avatar of 1,752 kWh
- In the real world energy consumption per capita ranges from 1,015 kWh to 7,702 kWh, depending on country
- For example, the average citizen of Brazil consumes <u>1,884 kWh</u>
- Hence, avatars (in about 2006) consume as much energy as Brazilians!
- "Avatars don't have bodies, but they do leave footprints."

Acknowledgement: Jerry Bautista, Intel

#### **Outline**

Topics looked at tonight:

- Space exploration
- Supercomputing
- Datacenters
- Consumer Electronics
- Medical Implants



- Studied Physics at Reed College in Portland,
   Oregon
- Ph.D. in Aeronautics, California Institute of Technology, 1993
- Taught Mechanical and Aerospace Engineering at Illinois Institute of Technology
- In 1996 joined NASA's Jet Propulsion Laboratory in Pasadena, California
- Has been involved in several technology development and JPL flight projects
- Since 2009 has been Supervisor of the Power Systems Engineering Group of the Power and Autonomous Systems Section

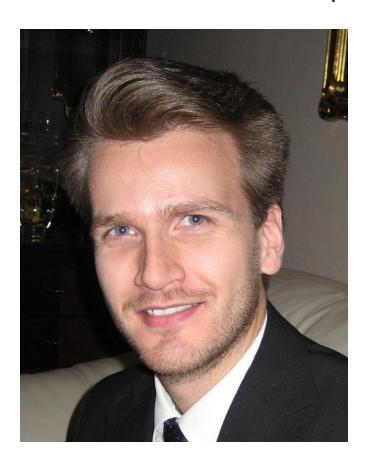
#### **Space Exploration**

**Greg Cardell** 

Power Systems Engineering Group Supervisor, Jet Propulsion Laboratory

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- M.S., University of Lulea, Sweden, 1996
- Ph.D., University of Utah, 2004
- Since 2001 has been with the Design Automation and Microarchitecture departments at IBM T. J. Watson Research Center
- Has developed power modeling methodologies and tools currently in use in IBM microprocessor design
- Has been part of the power modeling, design, and verification of several IBM microprocessors and test chips
- Is currently power lead for a future IBM processor chip

#### Supercomputing

Hans Jacobson Research Staff Member, IBM Corporation

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- M.S. in EE, Brigham Young University, Utah
- Intel Fellow and director of I/O research in Intel's Microprocessor Technology Lab, part of Intel Labs
- Joined Intel in 1992 and is responsible for circuit and interconnect research for multigigabit, chip-to-chip connections on microprocessor platforms
- Has been instrumental in driving consolidation of Intel's processor platform interconnect roadmap
- Pioneered fundamental circuit technology used in technologies such as PCI Express
- Holds 39 patents

#### **Datacenters**

Randy Mooney
Intel Fellow & Director I/O Research, Intel Corporation



- Joined Microsoft in 2008
- General Manager for IC Packaging, Silicon
   Operations, Quality and Reliability
- Covers all hardware products in Microsoft, including Xbox, Accessories, Zune, Keyboard, Mice, Webcam, Roundtable etc.
- From 1996 to 2008 was Corporate Fellow and Chief Technologist at AMD
- Led organic packaging development and manufacturing into high volume production
- Previously spent 21 years at IBM where he was Senior Technical Staff member
- Holds 50 US patents
- Published over 80 technical papers

#### **Consumer Electronics**

Raj Master

General Manager, IC Packaging, Quality and Reliability, Microsoft Corporation



- Joined Department of Electrical Engineering at Arizona State University in 2001
- Professor and Associate Dean of Research
- Director of both Connection One and WINTech research centers
- Connection One is a National Science
   Foundation Industry/University Cooperative
   Research Center established by ASU to
   enable an all-in-one communication device
- WINTech is research center for enabling development of fully autonomous nanoscale communication devices and systems
- Published over 100 technical papers

#### **Medical Implants**

Sayfe Kiaei

Associate Dean of Research, School of ECEE, Arizona State University